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COPPER SOLDER[View Images \(1 pages\)](#) | [View INPADOC only](#)Country: **JP Japan**

Kind:

Inventor(s): **HARA KENJI  
IKEDA MITSUAKI**Applicant(s): **YASKAWA ELECTRIC MFG CO LTD**  
[News, Profiles, Stocks and More about this company](#)Issued/Filed Dates: **Jan. 25, 1983 / July 17, 1981**Application Number: **JP1981000110756**IPC Class: **B23K 35/30; C22C 9/04;**

Abstract: **Purpose:** To provide phosphor copper solder with which restrained cracking is difficult to arise by mixing and melting specific ratios of phosphor, zinc, copper, titanium, and zirconium.  
**Constitution:** Phosphor copper contg., by weight %, 1W9% phosphor, 0.5W45% zinc, 52W83.5% copper, and 0.05W1.5% titanium and/or zirconium is produced by melting. Despite the restraining of base materials, said phosphor copper solder does not generate any micro-cracks, is easy to work with and is obtainable at a low cost.  
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Other Abstract Info: **CHEMABS 099(04)026680R**Foreign References: **(No patents reference this one)****Nominate this  
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